



(0.80 mm) .0315"

RU8-160-25-SE-L-DV-BL

HSC8-050-02-19-DP

RU8, HSC8 SERIES

HIGH SPEED RISER CARD KIT

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?RU8

Connector:

Insulator Material:

Black LCP

Contact: BeCu

Plating:

Au or Sn over

50µ" (1.27 µm) Ni

Current Rating:

3.1 A per pin

(6 adjacent pins powered)

Operating Temp:

-55°C to +125°C

Processing:

Lead-Free Solderable: Yes

SMT Lead Coplanarity:

(0.10 mm) .004" max (40-60)

RoHS Compliant: Yes

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



Note: While optimized for 50Ω applications, this connector with alternative signal/ground patterns may also perform well in certain 75Ω applications. Contact Samtec for further information.

Note: Some lengths, styles and options are non-standard, non-returnable.



RU8

1 POSITIONS PER ROW

STACK HEIGHT

SIGNAL ROUTING

PLATING OPTION

DV

BL

OTHER OPTION

40, 50, 60

-19
= (19 mm) .748"

-25
= (25 mm) .984"

-30
= (30 mm) 1.180"

-SE
= Single-Ended

-DP
= Differential Pair

-L
= 10µ" (0.25 µm) Gold on contact, Matte Tin on tail (Plating for connectors) Plating for Card is Hard Gold

-BL
= Board Locks (Bottom Socket only) (Not available on -19 stack height)

-K
= (5.50 mm) .217" DIA Polyimide Film Pick & Place Pad

-TR
= Tape & Reel

Kit contains two connectors and one card. Assembly required.

Diagram labels: -SE, -DP, -19 Only, -BL (Required with -25 & -30)

Dimensions: (7.98) .314, (1.60) .062, (7.01) .276, (12.51) .492

NO. OF POSITIONS PER SIDE	A	B	-SE TOTAL SIGNAL LINES	-DP TOTAL SIGNAL PAIRS
40	(39.80) 1.567	(51.05) 2.010	40	26
50	(47.80) 1.882	(59.05) 2.325	50	32
60	(55.80) 2.197	(67.05) 2.640	60	38

Note: Other Gold plating options available. Contact Samtec.

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40	(39.80) 1.567	(51.05) 2.010	40	26
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Finalinch
CERTIFIED

RU8 25 mm Stack Height	Rated @ 3dB Insertion Loss*
Single-Ended Signaling	7.5 GHz / 15 Gbps
Differential Pair Signaling	7.5 GHz / 15 Gbps

*Performance data includes effects of a non-optimized PCB. Performance data for other stack heights and complete test data available at www.samtec.com?RU8 or contact sig@samtec.com

Mates with:

HSEC8

SPECIFICATIONS

For complete specifications see www.samtec.com?HSC8

Conductor:

1/2 oz Copper

Contact Area:

Hard Gold Plated

Insulator: FR-4

RoHS Compliant: Yes

NO. OF POSITIONS PER SIDE	-SE TOTAL SIGNAL LINES	-DP TOTAL SIGNAL PAIRS
-040	40	26
-050	50	32
-060	60	38

Note: Some sizes, styles and options are non-standard, non-returnable.

HSC8

NUMBER OF POSITIONS PER SIDE

CARD STYLE

STACK HEIGHT

SIGNAL ROUTING

-040, -050, -060

-02
= (1.60 mm) .062" thick card

-19
= (19 mm) .748"

-25
= (25 mm) .984"

-30
= (30 mm) 1.180"

-SE
= Single-Ended

-DP
= Differential Pair

No. of Positions per Side x (0.80) .0315 + (4.45) .175

Diagram labels: Signal, Ground, -SE, -DP

Dimensions: (1.60) .062, A

STACK HEIGHT	A
-19	(14.84) .584
-25	(20.84) .820
-30	(25.84) 1.017